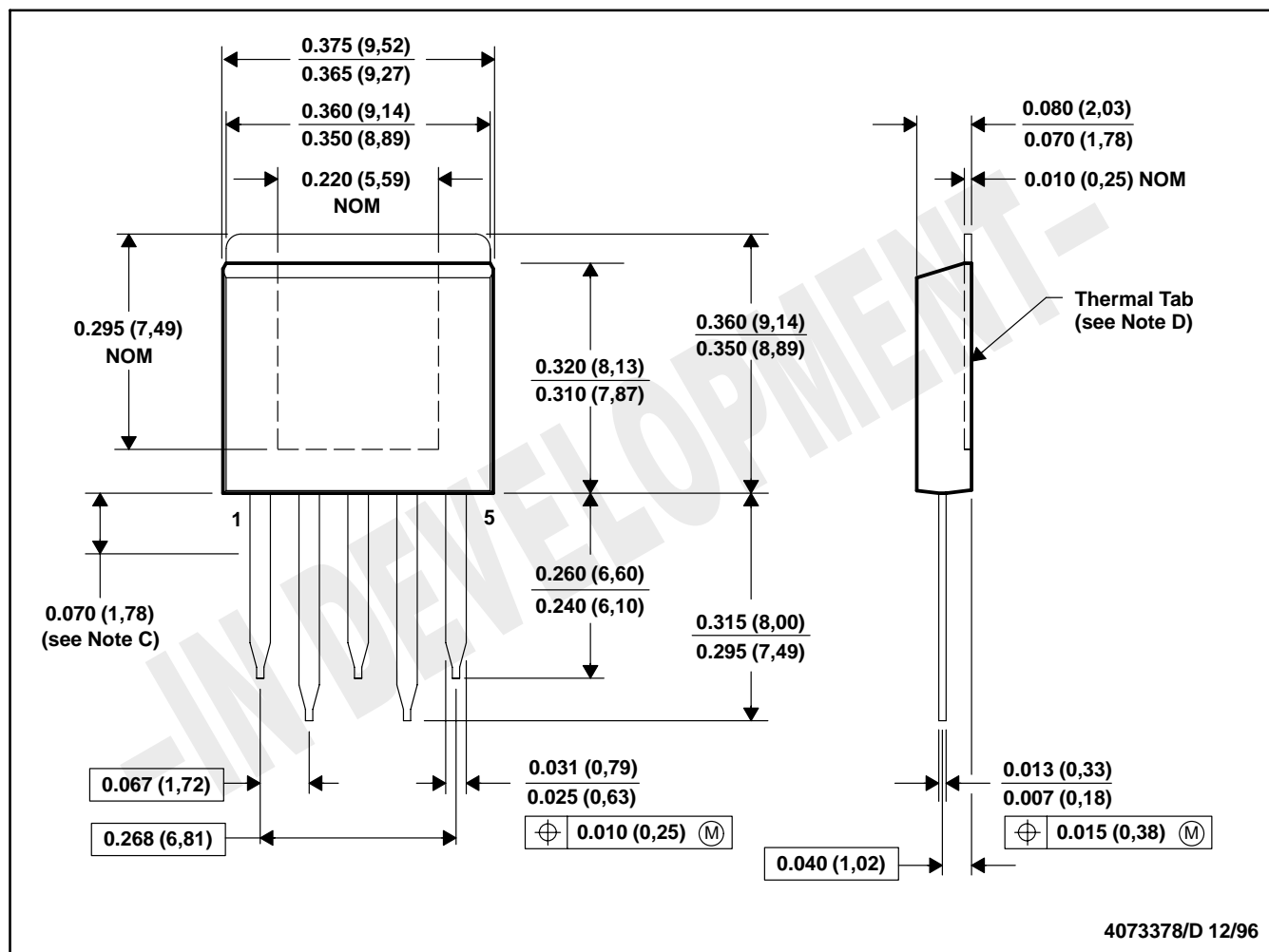


## KTH (R-PSFM-T5)

## PowerFLEX™ PLASTIC FLANGE-MOUNT PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Lead width not controlled in this area
  - D. The center lead is in electrical contact with the thermal tab.
  - E. Dimensions do not include mold protrusions, not to exceed 0.006 (0,15).

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